



Material Content Data Sheet



Sales Product Name		XDPL8220		Issued		20. July 2018		
MA#		MA001401894						
Package		PG-DSO-16-21		Weight*		175.34 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.847	2.76	2.76	27642	27642
leadframe	inorganic material	phosphorus	7723-14-0	0.023	0.01		129	
	non noble metal	zinc	7440-66-6	0.091	0.05		517	
	non noble metal	iron	7439-89-6	1.813	1.03		10338	
wire	non noble metal	copper	7440-50-8	73.601	41.98	43.07	419765	430749
	noble metal	palladium	7440-05-3	0.001	0.00		5	
	non noble metal	copper	7440-50-8	0.091	0.05	0.05	517	522
encapsulation	organic material	carbon black	1333-86-4	0.274	0.16		1562	
	plastics	epoxy resin	-	8.854	5.05		50499	
	inorganic material	silicondioxide	60676-86-0	82.153	46.86	52.07	468543	520604
leadfinish	non noble metal	tin	7440-31-5	1.562	0.89	0.89	8910	8910
plating	noble metal	silver	7440-22-4	0.641	0.37	0.37	3656	3656
glue	plastics	acrylic resin	-	0.305	0.17		1742	
	noble metal	silver	7440-22-4	1.083	0.62	0.79	6175	7917
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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